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CLAIMS

1. A method of producing a mask for use in producing a resist pattern for etching of a printed circuit, comprising defining in the mask a constant width etch band delineating the desired printed circuit conductor pattern.
2. A method according to claim 1 wherein the etch band is of substantially the same width as the narrowest conductor or the narrowest separation between conductors in the printed circuit.
3. A method according to claim 1 wherein the etch band separates the desired printed circuit conductor pattern from regions of unused conductor on the printed circuit.
4. A method according to claim 1, 2 or 3 wherein the printed circuit conductor pattern includes conductor regions less than about 30 microns wide.
5. A method according to claim 1, 2, 3 or 4 wherein the printed circuit conductor pattern includes conductor regions spaced by less than about 30 microns.
6. A method according to any one of the preceding claims wherein the etch band is less than about 30 microns wide.
7. A mask for use in producing a resist pattern for etching of a printed circuit, the mask being produced by the method of any one of the preceding claims.
8. A printed circuit in which the printed circuit elements are delineated by a constant width etch band.
9. A printed circuit according to claim 8 in which the etch band separates

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the printed circuit elements from regions of unused conductor.

10. A printed circuit according to claim 8 or 9 wherein the etch band is of substantially the same width as the narrowest conductor or the narrowest separation between conductors in the printed circuit.

11. A printed circuit according to claim 8, 9 or 10 wherein the printed circuit conductor pattern includes conductor regions less than about 30 microns wide.

12. A printed circuit according to claim 8, 9, 10 or 11 wherein the printed circuit conductor pattern includes conductor regions spaced by less than about 30 microns.

13. A printed circuit according to any one of claims 8 to 12 wherein the etch band is less than 30 microns wide.

14. A method of producing a printed circuit comprising a pattern of conductor elements, the method comprising the steps of: defining on a printed circuit substrate a pattern of resist to leave exposed regions of conductor to be etched away, the exposed regions comprising areas of constant width delineating the conductor elements.

15. A method according to claim 14 wherein the conductor elements include elements less than about 30 microns wide.

16. A method according to claim 14 or 15 wherein the pattern includes conductor elements spaced by less than about 30 microns.

17. A method according to claim 14, 15 or 16 wherein the regions of constant width are of substantially the same width as the narrowest element or narrowest separation between elements in the printed circuit.

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Country	Year	Population (millions)	Urban population (millions)	Urban population (%)	Population density (per sq km)	Urban population density (per sq km)	Population growth rate (%)	Urban population growth rate (%)	Population growth rate (%)	Urban population growth rate (%)	Population growth rate (%)	Urban population growth rate (%)
Algeria	1980	12.1	4.1	33.9	10.1	24.6	1.8	2.1	1.8	2.1	1.8	2.1
Algeria	1985	13.1	4.6	35.1	11.1	26.1	1.9	2.2	1.9	2.2	1.9	2.2
Algeria	1990	14.1	5.1	36.2	12.1	27.1	2.0	2.3	2.0	2.3	2.0	2.3
Algeria	1995	15.1	5.6	37.1	13.1	28.1	2.1	2.4	2.1	2.4	2.1	2.4
Algeria	2000	16.1	6.1	37.9	14.1	29.1	2.2	2.5	2.2	2.5	2.2	2.5
Algeria	2005	17.1	6.6	38.6	15.1	30.1	2.3	2.6	2.3	2.6	2.3	2.6
Algeria	2010	18.1	7.1	39.2	16.1	31.1	2.4	2.7	2.4	2.7	2.4	2.7
Algeria	2015	19.1	7.6	39.8	17.1	32.1	2.5	2.8	2.5	2.8	2.5	2.8
Algeria	2020	20.1	8.1	40.3	18.1	33.1	2.6	2.9	2.6	2.9	2.6	2.9
Algeria	2025	21.1	8.6	40.8	19.1	34.1	2.7	3.0	2.7	3.0	2.7	3.0
Algeria	2030	22.1	9.1	41.2	20.1	35.1	2.8	3.1	2.8	3.1	2.8	3.1
Algeria	2035	23.1	9.6	41.6	21.1	36.1	2.9	3.2	2.9	3.2	2.9	3.2
Algeria	2040	24.1	10.1	41.9	22.1	37.1	3.0	3.3	3.0	3.3	3.0	3.3
Algeria	2045	25.1	10.6	42.2	23.1	38.1	3.1	3.4	3.1	3.4	3.1	3.4
Algeria	2050	26.1	11.1	42.5	24.1	39.1	3.2	3.5	3.2	3.5	3.2	3.5
Algeria	2055	27.1	11.6	42.8	25.1	40.1	3.3	3.6	3.3	3.6	3.3	3.6
Algeria	2060	28.1	12.1	43.1	26.1	41.1	3.4	3.7	3.4	3.7	3.4	3.7
Algeria	2065	29.1	12.6	43.3	27.1	42.1	3.5	3.8	3.5	3.8	3.5	3.8
Algeria	2070	30.1	13.1	43.5	28.1	43.1	3.6	3.9	3.6	3.9	3.6	3.9
Algeria	2075	31.1	13.6	43.7	29.1	44.1	3.7	4.0	3.7	4.0	3.7	4.0
Algeria	2080	32.1	14.1	43.9	30.1	45.1	3.8	4.1	3.8	4.1	3.8	4.1
Algeria	2085	33.1	14.6	44.1	31.1	46.1	3.9	4.2	3.9	4.2	3.9	4.2
Algeria	2090	34.1	15.1	44.3	32.1	47.1	4.0	4.3	4.0	4.3	4.0	4.3
Algeria	2095	35.1	15.6	44.4	33.1	48.1	4.1	4.4	4.1	4.4	4.1	4.4
Algeria	2100	36.1	16.1	44.6	34.1	49.1	4.2	4.5	4.2	4.5	4.2	4.5
Algeria	2105	37.1	16.6	44.7	35.1	50.1	4.3	4.6	4.3	4.6	4.3	4.6
Algeria	2110	38.1	17.1	44.9	36.1	51.1	4.4	4.7	4.4	4.7	4.4	4.7
Algeria	2115	39.1	17.6	45.0	37.1	52.1	4.5	4.8	4.5	4.8	4.5	4.8
Algeria	2120	40.1	18.1	45.1	38.1	53.1	4.6	4.9	4.6	4.9	4.6	4.9
Algeria	2125	41.1	18.6	45.2	39.1	54.1	4.7	5.0	4.7	5.0	4.7	5.0
Algeria	2130	42.1	19.1	45.3								